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## Six Output Differential Buffer for PCle Gen3

9DB633

#### **Recommended Application:**

6 output PCIe Gen3 zero-delay/fanout buffer

#### **General Description:**

The 9DB633 zero-delay buffer supports PCIe Gen3 requirements, while being backwards compatible to PCIe Gen2 and Gen1. The 9DB633 is driven by a differential SRC output pair from an IDT 932S421 or 932SQ420 or equivalent main clock generator. It attenuates jitter on the input clock and has a selectable PLL bandwidth to maximize performance in systems with or without Spread-Spectrum clocking. An SMBus interface allows control of the PLL bandwidth and bypass options, while 2 clock request (OE#) pins make the 9DB633 suitable for Express Card applications.

#### **Key Specifications:**

- Cycle-to-cycle jitter < 50 ps</li>
- Output-to-output skew < 50 ps
- PCIe Gen3 phase jitter < 1.0ps RMS

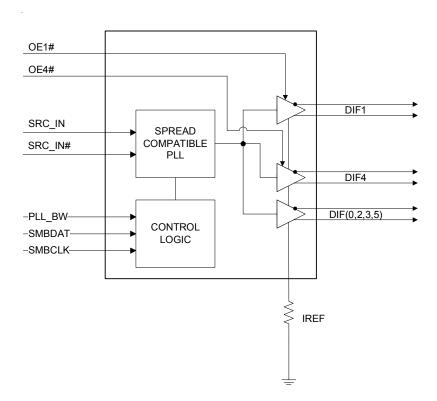
#### Features/Benefits:

- OE# pins/Suitable for Express Card applications
- PLL or bypass mode/PLL can dejitter incoming clock
- Selectable PLL bandwidth/minimizes jitter peaking in downstream PLL's
- Spread Spectrum Compatible/tracks spreading input clock for low EMI
- · SMBus Interface/unused outputs can be disabled

#### **Output Features:**

6 - 0.7V current mode differential HCSL output pairs

#### **Block Diagram**



## **Pin Configuration**

PLL BW	4		20	VD DA
_				
SRC_IN	2		27	GNDA
SRC_IN#	3		26	IREF
vOE1#	4		25	vOE4#
DIF_0	5		24	DIF_5
DIF_0#	6	633	23	DIF_5#
VDD	7		22	VD D
GND	8	08	21	GND
DIF_1	9	16	20	DIF_4
DIF_1#	10		19	DIF_4#
DIF_2	11		18	DIF_3
DIF_2#	12		17	DIF_3#
VDD	13		16	VD D
SMBDAT	14		15	SMBCLK

Note:Pins preceeded by 'v' have internal 120K ohm pull down resistors

## **Power Distribution Table**

Pin N	lumber	Description			
VDD	GND	Description			
7, 13, 16, 22	8,21	Differential Outputs			
13	8	SMBus			
N/A	27	IREF			
28	27	Analog VDD & GND for PLL core			

## **Pin Description**

PIN#	PIN NAME	PIN TYPE	DESCRIPTION
1	PLL BW	IN	3.3V input for selecting PLL Band Width
'	T LL_DVV	111	0 = low, 1= high
2	SRC_IN	IN	0.7 V Differential SRC TRUE input
3	SRC_IN#	IN	0.7 V Differential SRC COMPLEMENTARY input
4	vOE1#	IN	Active low input for enabling DIF pair 1. This pin has an internal pull-down.  1 =disable outputs, 0 = enable outputs
5	DIF_0	OUT	0.7V differential true clock output
6	DIF_0#	OUT	0.7V differential Complementary clock output
7	VDD	PWR	Power supply, nominal 3.3V
8	GND	IN	Ground pin.
9	DIF_1	OUT	0.7V differential true clock output
10	DIF_1#	OUT	0.7V differential Complementary clock output
11	DIF_2	OUT	0.7V differential true clock output
12	DIF_2#	OUT	0.7V differential Complementary clock output
13	VDD	PWR	Power supply, nominal 3.3V
14	SMBDAT	I/O	Data pin of SMBUS circuitry, 5V tolerant
15	SMBCLK	IN	Clock pin of SMBUS circuitry, 5V tolerant
16	VDD	PWR	Power supply, nominal 3.3V
17	DIF_3#	OUT	0.7V differential Complementary clock output
18	DIF_3	OUT	0.7V differential true clock output
19	DIF_4#	OUT	0.7V differential Complementary clock output
20	DIF_4	OUT	0.7V differential true clock output
21	GND	PWR	Ground pin.
22	VDD	PWR	Power supply, nominal 3.3V
23	DIF_5#	OUT	0.7V differential Complementary clock output
24	DIF_5	OUT	0.7V differential true clock output
25	vOE4#	IN	Active low input for enabling DIF pair 4. This pin has an internal pull-down.  1 =disable outputs, 0 = enable outputs
26	IREF	OUT	This pin establishes the reference for the differential current-mode output pairs. It requires a fixed precision resistor to ground. 4750hm is the standard value for 1000hm differential impedance. Other impedances require different values. See data sheet.
27	GNDA	PWR	Ground pin for the PLL core.
28	VDDA	PWR	3.3V power for the PLL core.

#### Note:

Pins preceded by 'v' have internal 120K ohm pull down resistors

**Electrical Characteristics - Absolute Maximum Ratings** 

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
3.3V Core Supply Voltage	VDDA				4.6	V	1,2
3.3V Logic Supply Voltage	VDD				4.6	V	1,2
Input Low Voltage	$V_{IL}$		GND-0.5			V	1
Input High Voltage	$V_{IH}$	Except for SMBus interface			V <sub>DD</sub> +0.5V	V	1
Input High Voltage	$V_{IHSMB}$	SMBus clock and data pins			5.5V	٧	1
Storage Temperature	Ts		-65		150	°C	1
Junction Temperature	Tj				125	ç	1
Input ESD protection	ESD prot	Human Body Model	2000			٧	1

<sup>&</sup>lt;sup>1</sup>Guaranteed by design and characterization, not 100% tested in production.

#### **Electrical Characteristics - Input/Supply/Common Parameters**

 $TA = T_{COM}$  or  $T_{IND}$ : Supply Voltage VDD = 3.3 V +/-5%

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Ambient Operating	T <sub>COM</sub>	Commmercial range	0		70	°C	1
Temperature	T <sub>IND</sub>	Industrial range	-40		85	°C	1
Input High Voltage	V <sub>IH</sub>	Single-ended inputs, except SMBus, low threshold and tri-level inputs	2		V <sub>DD</sub> + 0.3	٧	1
Input Low Voltage	$V_{IL}$	Single-ended inputs, except SMBus, low threshold and tri-level inputs	GND - 0.3		0.8	٧	1
	I <sub>IN</sub>	Single-ended inputs, $V_{IN} = GND$ , $V_{IN} = VDD$	-5		5	uA	1
Input Current	I <sub>INP</sub>	$\label{eq:VIN} Single-ended inputs $$V_{IN}=0\ V;$ Inputs with internal pull-up resistors $$V_{IN}=VDD;$ Inputs with internal pull-down resistors $$V_{IN}=VDD;$ Inputs $V_{IN}=VDD;$ Inputs $V_{IN}$	-200		200	uA	1
Input Frequency	$F_{ibyp}$	V <sub>DD</sub> = 3.3 V, Bypass mode	10		110	MHz	2
input Frequency	F <sub>ipII</sub>	$V_{DD} = 3.3 \text{ V}$ , 100MHz PLL mode	33	100.00	110	MHz	2
Pin Inductance	$L_{pin}$				7	nΗ	1
	C <sub>IN</sub>	Logic Inputs, except DIF_IN	1.5		5	pF	1
Capacitance	C <sub>INDIF_IN</sub>	DIF_IN differential clock inputs	1.5		2.7	pF	1,4
	C <sub>OUT</sub>	Output pin capacitance			6	pF	1
Clk Stabilization	T <sub>STAB</sub>	From V <sub>DD</sub> Power-Up and after input clock stabilization or de-assertion of PD# to 1st clock			1.8	ms	1,2
Input SS Modulation Frequency	f <sub>MODIN</sub>	Allowable Frequency (Triangular Modulation)	30		33	kHz	1
OE# Latency	t <sub>LATOE#</sub>	DIF start after OE# assertion DIF stop after OE# deassertion	1		3	cycles	1,3
Tdrive_PD#	t <sub>DRVPD</sub>	DIF output enable after PD# de-assertion			300	us	1,3
Tfall	$t_{F}$	Fall time of control inputs			5	ns	1,2
Trise	t <sub>R</sub>	Rise time of control inputs			5	ns	1,2
SMBus Input Low Voltage	$V_{ILSMB}$				0.8	V	1
SMBus Input High Voltage	$V_{IHSMB}$		2.1		$V_{\rm DDSMB}$	V	1
SMBus Output Low Voltage	$V_{OLSMB}$	@ I <sub>PULLUP</sub>			0.4	٧	1
SMBus Sink Current	I <sub>PULLUP</sub>	@ V <sub>OL</sub>	4			mA	1
Nominal Bus Voltage	$V_{DDSMB}$	3V to 5V +/- 10%	2.7		5.5	V	1
SCLK/SDATA Rise Time	t <sub>RSMB</sub>	(Max VIL - 0.15) to (Min VIH + 0.15)			1000	ns	1
SCLK/SDATA Fall Time	t <sub>FSMB</sub>	(Min VIH + 0.15) to (Max VIL - 0.15)			300	ns	1
SMBus Operating Frequency	f <sub>MAXSMB</sub>	Maximum SMBus operating frequency			100	kHz	1,5

 $<sup>^{1}\</sup>mbox{Guaranteed}$  by design and characterization, not 100% tested in production.

<sup>&</sup>lt;sup>2</sup> Operation under these conditions is neither implied nor guaranteed.

 $<sup>^2\</sup>mbox{Control}$  input must be monotonic from 20% to 80% of input swing.

<sup>&</sup>lt;sup>3</sup>Time from deassertion until outputs are >200 mV

<sup>&</sup>lt;sup>4</sup>DIF\_IN input

<sup>&</sup>lt;sup>5</sup>The differential input clock must be running for the SMBus to be active

#### Electrical Characteristics - DIF\_IN Clock Input Parameters

T<sub>AMB</sub>=T<sub>COM</sub> or T<sub>IND</sub> unless otherwise indicated, Supply Voltages per normal operation conditions, See Test Loads for Loading Conditions

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Input Crossover Voltage - DIF_IN	V <sub>CROSS</sub>	Cross Over Voltage	150	375	900	mV	1
Input Swing - DIF_IN	V <sub>SWING</sub>	Differential value	300			mV	1
Input Slew Rate - DIF_IN	dv/dt	Measured differentially	1		8	V/ns	1,2
Input Leakage Current	I <sub>IN</sub>	$V_{IN} = V_{DD}$ , $V_{IN} = GND$	-5		5	uA	
Input Duty Cycle	$d_{tin}$	Measurement from differential wavefrom	45		55	%	1
Input Jitter - Cycle to Cycle	$J_{DIFIn}$	Differential Measurement	0		125	ps	1

<sup>&</sup>lt;sup>1</sup> Guaranteed by design and characterization, not 100% tested in production.

#### **Electrical Characteristics - DIF 0.7V Current Mode Differential Outputs**

 $T_A = T_{COM}$  or  $T_{IND}$ ; Supply Voltage VDD = 3.3 V +/-5%

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Slew rate	Trf	Scope averaging on	0.6	2.5	4	V/ns	1, 2, 3
Slew rate matching	ΔTrf	Slew rate matching, Scope averaging on		9.5	20	%	1, 2, 4
Voltage High	VHigh	Statistical measurement on single-ended signal using oscilloscope math function. (Scope averaging	660	740	850	mV	1
Voltage Low	VLow	on)	-150	8	150	IIIV	1
Max Voltage	Vmax	Measurement on single ended signal using absolute		760	1150	mV	1
Min Voltage	Vmin	value. (Scope averaging off)	-300	-3		IIIV	1
Vswing	Vswing	Scope averaging off	300	1506		mV	1, 2
Crossing Voltage (abs)	Vcross_abs	Scope averaging off	250	378	550	mV	1, 5
Crossing Voltage (var)	∆-Vcross	Scope averaging off		54	140	mV	1, 6

<sup>&</sup>lt;sup>1</sup>Guaranteed by design and characterization, not 100% tested in production. IREF = VDD/(3xR<sub>R</sub>). For R<sub>R</sub> = 475Ω (1%), I<sub>REF</sub> = 2.32mA. I<sub>OH</sub> =  $6 \times I_{REF}$  and  $V_{OH}$  = 0.7V @  $Z_{O}$ =50Ω (100Ω differential impedance).

#### **Electrical Characteristics - Current Consumption**

TA = T<sub>COM</sub> or T<sub>IND</sub>: Supply Voltage VDD = 3.3 V +/-5%

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Operating Supply Current	I <sub>DD3.3OP</sub>	All outputs active @100MHz, C <sub>L</sub> = Full load;		134	150	mA	1
Powerdown Current	I <sub>DD3.3PD</sub>	All diff pairs driven			N/A	mA	1
Fowerdown Current	I <sub>DD3.3PDZ</sub>	All differential pairs tri-stated			N/A	mA	1

<sup>&</sup>lt;sup>1</sup>Guaranteed by design and characterization, not 100% tested in production.

<sup>&</sup>lt;sup>2</sup>Slew rate measured through +/-75mV window centered around differential zero

<sup>&</sup>lt;sup>2</sup> Measured from differential waveform

<sup>&</sup>lt;sup>3</sup> Slew rate is measured through the Vswing voltage range centered around differential 0V. This results in a +/-150mV window around differential 0V.

<sup>&</sup>lt;sup>4</sup> Matching applies to rising edge rate for Clock and falling edge rate for Clock#. It is measured using a +/-75mV window centered on the average cross point where Clock rising meets Clock# falling. The median cross point is used to calculate the voltage thresholds the oscilloscope is to use for the edge rate calculations.

<sup>&</sup>lt;sup>5</sup> Vcross is defined as voltage where Clock = Clock# measured on a component test board and only applies to the differential rising edge (i.e. Clock rising and Clock# falling).

<sup>&</sup>lt;sup>6</sup> The total variation of all Vcross measurements in any particular system. Note that this is a subset of V\_cross\_min/max (V\_cross absolute) allowed. The intent is to limit Vcross induced modulation by setting V\_cross\_delta to be smaller than V\_cross absolute.

## Electrical Characteristics - Output Duty Cycle, Jitter, Skew and PLL Characterisitics

 $TA = T_{COM}$  or  $T_{IND}$ : Supply Voltage VDD = 3.3 V +/-5%

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
PLL Bandwidth	BW	-3dB point in High BW Mode	2	2.3	4	MHz	1
PLL Bandwidth	DVV	-3dB point in Low BW Mode	0.4	0.5	1	MHz	1
PLL Jitter Peaking	t <sub>JPEAK</sub>	Peak Pass band Gain		1	2	dB	1
Duty Cycle	t <sub>DC</sub>	Measured differentially, PLL Mode	45	48	55	%	1
Duty Cycle Distortion	t <sub>DCD</sub>	Measured differentially, Bypass Mode @100MHz	-2	1	2	%	1,4
Ckow Input to Output	t <sub>pdBYP</sub>	Bypass Mode, V <sub>T</sub> = 50%	2500	3660	4500	ps	1
Skew, Input to Output	t <sub>pdPLL</sub>	Hi BW PLL Mode V <sub>T</sub> = 50%	-250	0	250	ps	1
Skew, Output to Output	t <sub>sk3</sub>	V <sub>T</sub> = 50%		15	50	ps	1
Jitter, Cycle to cycle	+.	PLL mode	•	40	50	ps	1,3
Jitter, Cycle to Cycle	t <sub>jcyc-cyc</sub>	Additive Jitter in Bypass Mode		10	50	ps	1,3

<sup>&</sup>lt;sup>1</sup>Guaranteed by design and characterization, not 100% tested in production.

#### **Electrical Characteristics - PCle Phase Jitter Parameters**

 $TA = T_{COM}$  or  $T_{IND}$ ; Supply Voltage VDD = 3.3 V +/-5%

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	Notes
	t <sub>iphPCleG1</sub>	PCIe Gen 1		32	86	ps (p-p)	1,2,3
	+	PCIe Gen 2 Lo Band 10kHz < f < 1.5MHz		1.1	3	ps (rms)	1,2
Phase Jitter, PLL Mode	<sup>T</sup> jphPCleG2	PCIe Gen 2 High Band 1.5MHz < f < Nyquist (50MHz)		2.3	3.1	ps (rms)	1,2
	t <sub>jphPCleG3</sub>	PCIe Gen 3 (PLL BW of 2-4MHz, CDR = 10MHz)		0.5	1	ps (rms)	1,2,4
	t <sub>jphPCleG1</sub>	PCIe Gen 1		2	5	ps (p-p)	1,2,3
Additive Phase Jitter,		PCIe Gen 2 Lo Band 10kHz < f < 1.5MHz		0.2	0.3	ps (rms)	1,2
Bypass Mode	t <sub>jphPCleG2</sub>	PCIe Gen 2 High Band 1.5MHz < f < Nyquist (50MHz)		0.8	1	ps (rms)	1,2
	t <sub>jphPCleG3</sub>	PCIe Gen 3 (PLL BW of 2-4MHz, CDR = 10MHz)		0.1	0.2	ps (rms)	1,2,4

<sup>&</sup>lt;sup>1</sup> Applies to all outputs.

 $<sup>^{2}\,</sup>I_{REF} = V_{DD}/(3xR_{R}). \ \ \, \text{For} \; R_{R} = 475\Omega \; (1\%), \; I_{REF} = 2.32 \text{mA}. \; I_{OH} = 6 \; x \; I_{REF} \; \text{and} \; V_{OH} = 0.7 V \; @ \; Z_{O} = 50\Omega. \; \, \ \, \text{The substitution of the su$ 

<sup>&</sup>lt;sup>3</sup> Measured from differential waveform

<sup>&</sup>lt;sup>4</sup> Duty cycle distortion is the difference in duty cycle between the output and the input clock when the device is operated in bypass mode.

<sup>&</sup>lt;sup>2</sup> See http://www.pcisig.com for complete specs

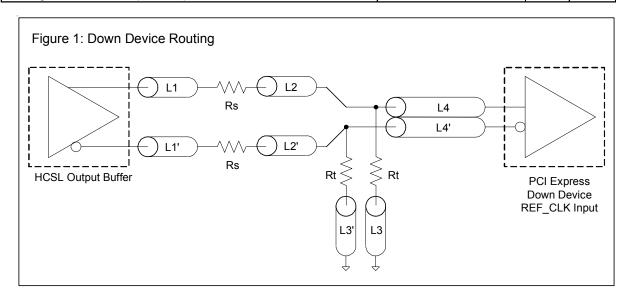
<sup>&</sup>lt;sup>3</sup> Sample size of at least 100K cycles. This figures extrapolates to 108ps pk-pk @ 1M cycles for a BER of 1-12.

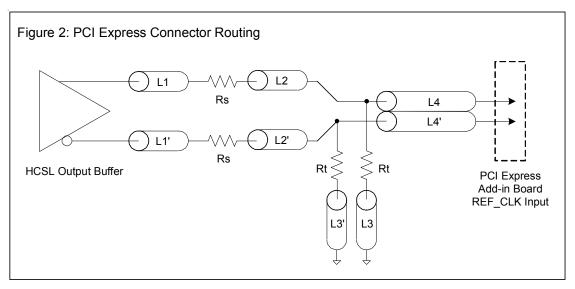
<sup>&</sup>lt;sup>4</sup> Subject to final radification by PCI SIG.

SRC Reference Clock			
Common Recommendations for Differential Routing	Dimension or Value	Unit	Figure
L1 length, route as non-coupled 50ohm trace	0.5 max	inch	1
L2 length, route as non-coupled 50ohm trace	0.2 max	inch	1
L3 length, route as non-coupled 50ohm trace	0.2 max	inch	1
Rs	33	ohm	1
Rt	49.9	ohm	1

Down Device Differential Routing			
L4 length, route as coupled microstrip 100ohm differential trace	2 min to 16 max	inch	1
L4 length, route as coupled stripline 100ohm differential trace	1.8 min to 14.4 max	inch	1

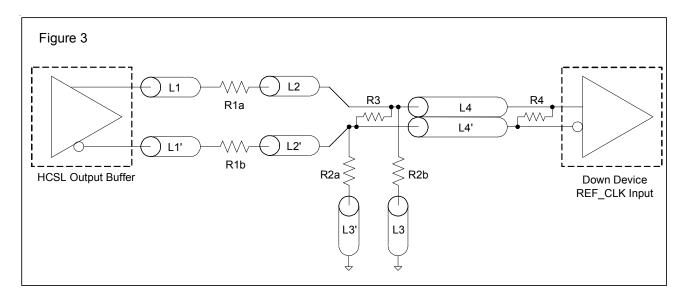
Differential Routing to PCI Express Connector			
L4 length, route as coupled microstrip 100ohm differential trace	0.25 to 14 max	inch	2
L4 length, route as coupled stripline 100ohm differential trace	0.225 min to 12.6 max	inch	2



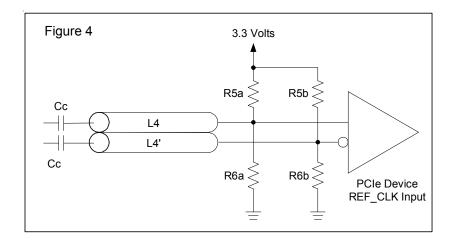


	Alternative Termination for LVDS and other Common Differential Signals (figure 3)								
Vdiff	Vp-p	Vcm	R1	R2	R3	R4	Note		
0.45v	0.22v	1.08	33	150	100	100			
0.58	0.28	0.6	33	78.7	137	100			
0.80	0.40	0.6	33	78.7	none	100	ICS874003i-02 input compatible		
0.60	0.3	1.2	33	174	140	100	Standard LVDS		

R1a = R1b = R1 R2a = R2b = R2



Cable Connected AC Coupled Application (figure 4)							
Component	Value	Note					
R5a, R5b	8.2K 5%						
R6a, R6b	1K 5%						
Сс	0.1 µF						
Vcm	0.350 volts						



## General SMBus serial interface information for the 9DB633

## **How to Write:**

- Controller (host) sends a start bit.
- Controller (host) sends the write address D4 (H)
- ICS clock will acknowledge
- Controller (host) sends the begining byte location = N
- ICS clock will acknowledge
- Controller (host) sends the data byte count = X
- ICS clock will acknowledge
- Controller (host) starts sending Byte N through Byte N + X -1 (see Note 2)
- ICS clock will acknowledge each byte one at a time
- · Controller (host) sends a Stop bit

## **How to Read:**

- · Controller (host) will send start bit.
- Controller (host) sends the write address D4<sub>(H)</sub>
- ICS clock will acknowledge
- Controller (host) sends the begining byte location = N
- ICS clock will acknowledge
- Controller (host) will send a separate start bit.
- Controller (host) sends the read address D5 (H)
- ICS clock will acknowledge
- ICS clock will send the data byte count = X
- ICS clock sends Byte N + X -1
- ICS clock sends Byte 0 through byte X (if X<sub>(H)</sub> was written to byte 8).
- Controller (host) will need to acknowledge each byte
- Controllor (host) will send a not acknowledge bit
- · Controller (host) will send a stop bit

Ind	ex Block W	/rit	e Operation
Coi	ntroller (Host)	ICS (Slave/Receiver)	
Т	starT bit		
Slav	e Address D4 <sub>(H)</sub>		
WR	WRite		
	•		ACK
Beg	inning Byte = N		
			ACK
Data	Byte Count = X		
			ACK
Begir	nning Byte N		
			ACK
	<b>\Q</b>	Ę.	
	<b>\rightarrow</b>	X Byte	<b>♦</b>
	<b>\Q</b>	×	<b>\Q</b>
		<b>\Q</b>	
Byt	e N + X - 1		
		ACK	
Р	stoP bit		

Ind	ex Block Rea				
Con	troller (Host)	IC	S (Slave/Receiver)		
Т	starT bit				
Slave	e Address D4 <sub>(H)</sub>				
WR	WRite				
	•		ACK		
Begii	nning Byte = N				
			ACK		
RT	Repeat starT				
Slave	e Address D5 <sub>(H)</sub>				
RD	ReaD				
			ACK		
		Data Byte Count = X			
	ACK				
			Beginning Byte N		
	ACK				
		/te	<b>O</b>		
	<b>O</b>	X Byte	0		
	0	$ \times $	0		
	0				
			Byte N + X - 1		
N	Not acknowledge				
Р	stoP bit				

SMBusTable: Device Control Register, READ/WRITE ADDRESS (D5/D4)

Byte	0	Pin #	Name	<b>Control Function</b>	Type	0	1	Default
Bit 7	-		SW_EN	Enables SMBus Control of bits (1:0)	RW	PLL controlled by SMBus registers	PLL controlled by device pins	1
Bit 6	-		RESE	RVED	RW	-		Χ
Bit 5	-		RESERVED RW -		•	Χ		
Bit 4	-		RESE	RVED	RW	-		Х
Bit 3	-		RESE	RVED	RW	-		Х
Bit 2	-		RESE	RVED	RW		-	Χ
Bit 1	-		PLL BW #adjust	Selects PLL Bandwidth	RW	Low BW	High BW	1
Bit 0	-		PLL Enable	Bypasses PLL for board test	RW	PLL bypassed (fan out mode)		1

SMBusTable: Output Enable Register

Byte	1 Pin #	Name	<b>Control Function</b>	Type	0	1	Default
Bit 7	•	RESI	ERVED	RW		-	X
Bit 6	•	RESI	ERVED	RW		-	X
Bit 5	24,23	PCIEX5	Output Control	RW	Disable	Enable	1
Bit 4	-	RESI	ERVED	RW	-		Χ
Bit 3	18,17	PCIEX3	Output Control	RW	Disable	Enable	1
Bit 2	11,12	PCIEX2	Output Control	RW	Disable	Enable	1
Bit 1	-	RESI	ERVED	RW	-		Х
Bit 0	5,6	PCIEX0	Output Control	RW	Disable	Enable	1

SMBusTable: Function Select Register

Byte	Byte 2 Pin #		Name	<b>Control Function</b>	Туре	0	1	Default
Bit 7			RESE	RVED	RW		-	X
Bit 6			RESE	RVED	RW	-		Х
Bit 5			RESE	RVED	D RW -		Х	
Bit 4			RESE	RESERVED RW -		-	Х	
Bit 3			RESE	RVED	RW		-	Х
Bit 2			RESERVED		RW		-	Χ
Bit 1	-		RESE	RVED	RW			Х
Bit 0	-		RESE	RVED	RW			Х

SMBusTable: Vendor & Revision ID Register

Byte	3 F	Pin #	Name	<b>Control Function</b>	Туре	0	1	Default
Bit 7			RID3		R	-	-	0
Bit 6	-		RID2	REVISION ID	R	-	-	0
Bit 5	-		RID1		R	-	-	0
Bit 4	-		RID0		R	-	-	1
Bit 3	-		VID3		R	-	-	0
Bit 2	-		VID2	VENDODID	R	-	-	0
Bit 1	•		VID1	VENDOR ID	R	-	-	0
Bit 0	-		VID0		R	-	-	1

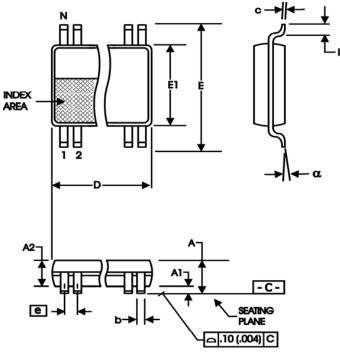
**SMBusTable: DEVICE ID** 

Byte	4	Pin #	Name	<b>Control Function</b>	Туре	0	1	Default
Bit 7	-				R		-	0
Bit 6	-				R		-	0
Bit 5		•			R		-	0
Bit 4	-	•	Devi	ice ID	R		-	0
Bit 3	-		= 06	6 Hex	R		-	0
Bit 2	-				R		-	1
Bit 1	-				R		-	1
Bit 0	-				R		-	0

SMBusTable: Byte Count Register

Byte	5	Pin #	Name	Control Function	Туре	0	1	Default
Bit 7	-	-	BC7		RW	-	-	0
Bit 6	-		BC6	Writing to this	RW	-	-	0
Bit 5	-	-	BC5	register will	RW	-	-	0
Bit 4	-		BC4	configure how	RW	-	-	0
Bit 3	-		BC3	many bytes will be	RW	-	-	0
Bit 2	-		BC2	read back, default	RW	-	-	1
Bit 1	-	-	BC1	is $06 = 6$ bytes.	RW	-	-	1
Bit 0	-	-	BC0		RW	-	-	0

# 28-pin SSOP Package Drawing and Dimensions



209 mil SSOP

209 mil SSOP

	In Milli	meters	In Inches		
SYMBOL	COMMON D	IMENSIONS	COMMON DIMENSIONS		
	MIN	MAX	MIN	MAX	
Α		2.00		.079	
A1	0.05		.002		
A2	1.65	1.85	.065	.073	
b	0.22	0.38	.009	.015	
С	0.09	0.25	.0035	.010	
D	SEE VAF	RIATIONS	SEE VARIATIONS		
E	7.40	8.20	.291	.323	
E1	5.00	5.60	.197	.220	
е	0.65 E	BASIC	0.0256	BASIC	
L	0.55	0.95	.022	.037	
N	SEE VARIATIONS		SEE VARIATIONS		
α	0°	8°	0°	8°	

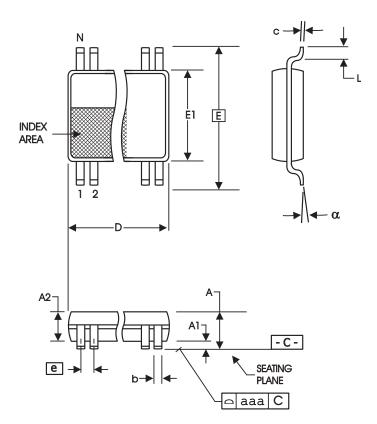
#### **VARIATIONS**

N	D mm.		D (inch)	
	MIN	MAX	MIN	MAX
28	9.90	10.50	.390	.413

Reference Doc.: JEDEC Publication 95, MO-150

10-0033

## 28-pin TSSOP Package Drawing and Dimensions



4.40 mm. Body, 0.65 mm. Pitch TSSOP (173 mil) (25.6 mil)

SYMBOL	In Millimeters		In Inches	
	COMMON DIMENSIONS		COMMON DIMENSIONS	
	MIN	MAX	MIN	MAX
Α		1.20		.047
A1	0.05	0.15	.002	.006
A2	0.80	1.05	.032	.041
b	0.19	0.30	.007	.012
С	0.09	0.20	.0035	.008
D	SEE VARIATIONS		SEE VARIATIONS	
E	6.40 BASIC		0.252 BASIC	
E1	4.30	4.50	.169	.177
е	0.65 BASIC		0.0256 BASIC	
L	0.45	0.75	.018	.030
N	SEE VARIATIONS		SEE VARIATIONS	
α	0°	8°	0°	8°
aaa		0.10		.004

#### **VARIATIONS**

N	D mm.		D (inch)	
	MIN	MAX	MIN	MAX
28	9.60	9.80	.378	.386

Reference Doc.: JEDEC Publication 95, MO-153

10-0035

# **Ordering Information**

Part / Order Number	Shipping Packaging	Package	Temperature
9DB633AFLF	Tubes	28-pin SSOP	0 to +70°C
9DB633AFLFT	Tape and Reel	28-pin SSOP	0 to +70°C
9DB633AFILF	Tubes	28-pin SSOP	-40 to +85°C
9DB633AFILFT	Tape and Reel	28-pin SSOP	-40 to +85°C
9DB633AGLF	Tubes	28-pin TSSOP	0 to +70°C
9DB633AGLFT	Tape and Reel	28-pin TSSOP	0 to +70°C
9DB633AGILF	Tubes	28-pin TSSOP	-40 to +85°C
9DB633AGILFT	Tape and Reel	28-pin TSSOP	-40 to +85°C

<sup>&</sup>quot;LF" after the package code are the Pb-Free configuration and are RoHS compliant.

<sup>&</sup>quot;A" is the device revision designator (will not correlate to the datasheet revision).

## **Revision History**

Originator	Issue Date	Description	Page #	
RDW	6/30/2010	Released to final		
RDW	7/12/2010	Changed "PWD" to "Default" in SMBus Register descriptions		
RDW	4/20/2011	Changed pull down indicator from '**' to 'v'.		
		Corrected typo for 28SSOP T&R orderable part number; "I" and "L" were		
RDW	10/22/2013	swapped.	13	
RDW	2/19/2014	Corrected typo for Read/Write address from D4/D5 to D5/D4 respectively	9,10	
RDW	10/20/2016	Updated input clock electrical table to latest format. No change to form, fit or function of the device	5	
	RDW RDW RDW RDW	RDW 6/30/2010 RDW 7/12/2010 RDW 4/20/2011  RDW 10/22/2013 RDW 2/19/2014	RDW 6/30/2010 Released to final  RDW 7/12/2010 Changed "PWD" to "Default" in SMBus Register descriptions  RDW 4/20/2011 Changed pull down indicator from '**' to 'v'.  Corrected typo for 28SSOP T&R orderable part number; "I" and "L" were swapped.  RDW 10/22/2013 swapped.  RDW 2/19/2014 Corrected typo for Read/Write address from D4/D5 to D5/D4 respectively	

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